

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMS/19/11619	
1.3 Title of PCN	New Molding Compound in TO92 package to replace SAMSUNG SDI under termination phase	
1.4 Product Category	See product list	
1.5 Issue date	2019-07-06	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANCKE CHRISTIANE
2.1.2 Phone	+49 89460062128
2.1.3 Email	christiane.francke@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Marcello SAN BIAGIO
2.1.3 Quality Manager	Sergio Tommaso SPAMPINATO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Mold compound	ASE WEIHAI - CHINA

4. Description of change

	Old	New
4.1 Description	Molding compound : SAMSUNG EMC type SG-8100GS	Molding compound : EMC GR30HT (Hysol Huawei) as first choice. While considering to qualify 2nd source as back-up (to update Rel result once available).
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	As anticipated by ST Corporate PCI No. CRP/19/11478, this PCN is to announce the replacement of current molding compound SAMSUNG EMC type SG-8100GS for TO 92 package assembled in ASE WEIHAI Plant
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	By internal codification and traceability code
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7. Timing / schedule

7.1 Date of qualification results	2019-06-11
7.2 Intended start of delivery	2019-09-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11619 11619_Samsung MC.zip		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-07-06

9. Attachments (additional documentations)

11619 Public product.pdf
11619 11619_Samsung MC.zip

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L4931CZ50-AP	
	L78L12ACZ	
	LE33CZ-AP	
	LM217LZ-TR	
	LM317LZ-AP	
	TL1431ACZ	
	TL431ACZT	

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